Basic Substance Crotentianed in r % to tail ppm 99.27 (mg) Total Mold Compound % of Total Weight 73.5 Silica, vitreous 60676-86-0 Mold Compound 61.21 7.64 61.307 Epox / Rein Trade Secret Mold Compound 61.21 7.64 61.307 Epox / Rein Trade Secret 5.61 Epox / Rein 10.55 Epox / Rein 10.5 Epox / Rein	Semiconductor Device Type: SM (C3X) 008 SOIJ .208in Matte Tin				Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			
Static statutation Cash number Output memory Number of the statute				% Iotal				()= ()			
$\frac{1}{1000} \frac{1}{1000} \frac{1}{1000$	Basic Substance	CAS Number	Sub-Component	Weight	mg/part	ppm	99.27	(mg) I otal	Mola Compound	% of Total Weight	/9.8
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Output degree and its homogenous materials comply with UDirectives: 2002/95/EC (27 January 2003) & Directive 2011/85/EU (08 June 2011) and 2015/863/EU (31 March 5) and 2002/35/EC (End-of-Life Vehicles (ELV) without exemption (tero) pailance with the above EU Directives has been verified with ententional ingrediate deal attains, and /or analytical test data. (ma) Teal (mg) Teal (mg	lin	7440-31-5						Modified Amine			<u> </u>
semiconductor device and its homogenous materials comply with EU Directives: 200295/EC (27 January 2003) & Directive 2011/BS/EU (08 June 2011) and 2015/863/EU (31 March 5) and 200275/EC (End-of-Life Vehicles (ELV) without examption (zero) 5) and 200275/EC (End-of-Life Vehicles (ELV) without examption (zero) b) and 200275/EC (End-of-Life Vehicles (ELV) without examption (zero) chemical substance is above. EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data. chemical substance is above. EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data. chemical substance is above. EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data. chemical substance is Above. EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data. the note device dup Microchip meet the ULS4 V0 filmmability standard for plastics. You can access the UL IQTM family of databases to obtain a test report at <i>Jul.comigOuldaleng/pages/offerings/industries/chemicals/plastics/</i> protective "tubes" in which the specific product is shipped are made from polyvinyl choride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and in "relet" may be made from PVC plastic. Total 100.00 Total 1.75 Paladum 7.40-05-8 98.25 Paladum 7.				100.000	124.400	1,000,000					
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plance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data. 100.00 themical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology is not believe that the unavoidable impurity concentration of the chemical substance, if is not below the threshold of regulatory concern for any regulatory scheme world-wide. 0.25 (mg) Total Wire Bond: Copper plantialities (CPH) is not the first above, the chemical substance is absent from the list above, the chemical substance is absent from the list above, the chemical substance is absent from the list above, the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at <i>X</i> /ulocmorg/bala/mig/sages/offering/sindustries/schemicals/plastics/ 0.25 (mg) Total Copper plantiality (mg) total Weight 0.2 Value.compload used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at <i>X</i> /ulocmorg/bala/mig/sages/offering/sages/sage/sage/sage/sage/sage/sage/sa							Doped Silicon	7440-21-3	100.00		
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c://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ Copper 7440-50-8 98.25 p:protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and tain "reels" may be made from PVC plastic. Image: Copper 7440-50-8 98.25 Palladium 7440-05-3 1.75 Torchip Technology Incorporated believes the information in this form concerning substances restricted by ROHS in Microchip Technology Incorporated's semiconductor devices in molecuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers. Stuppliers information in information may not have been provided by subcontract assemblers and raw material suppliers. Suppliers information is information and not merages excipted envices (silicon IC) in the finished parts. Image: Technology Incorporated does not provide any warranty, express or implied, with respect to the information provided in this declaration. The exclusive, limited product in Microchip's standard terms and conditions of sale. These are provided in Microchip's total molecular devices is a result of the users' reliance on the information in Material Content Declarations (MCD) or independent third party test reports (SGS) or his Certificate of Compliance for semiconductor products. Image: Technology Incorporated above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at	a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology corporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if ny, is not below the threshold of regulatory concern for any regulatory scheme world-wide.								Total	100.00	
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cructing incorportate does not provide any warranty, express or implied, with respect to the information provide in this declaration. The exclusive, initial product incrusing provided by Microchip Technology Incorporated and its subsidiaries are contained in Microchip's standard terms and conditions of sale. These are provided in Microchip's 1.56 (mg) Total leads (pins) - Matte Tin / annealed at 150°C for 1 hour % of Total Weight 1.25 crochip disclaims any duty to notify users of updates or changes to Material Content Declarations and shall not be liable for any damages, direct or indirect, consequential or terwise, suffered by users or third parties as a result of the users' reliance on the information in Material Content Declarations (MCD) or independent third party test reports (SGS) or this Certificate of Compliance for semiconductor products. Tin 7440-31-5 100.00 sembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at Total Total 100.00	orporated's knowledge and belief as of the date of this document, is not below the threshold of regulatory concern for any regula Iding compounds used by Microchip meet the UL94 V0 flammabi p://ul.com/global/eng/pages/offerings/industries/chemicals/plasti e protective "tubes" in which the specific product is shipped are tain "reels" may be made from PVC plastic.	s, there is no credi tory scheme work lity standard for p cs/ made from polyvi	an intentional ingredient in the semiconductor device and, ble reason to believe that the unavoidable impurity concer 4-wide. lastics. You can access the UL iQTM family of databases to nyl chloride (PVC) plastic. "Window envelopes" used to ho	ntration of the p obtain a test and the packing	chemical subs report at slip on the o	stance, if uter box and	0.25	Copper	Wire Bond - Copper, palladium coated (CuPd) 7440-50-8 7440-05-3	% of Total Weight 98.25 1.75	0.2
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